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HVV1011-035 PRODUCT OVERVIEW

L-Band Avionics Pulsed Power Transistor 1030-1090MHz, 50µs Pulse, 5% Duty for TCAS and Mode-S Applications

DESCRIPTION

The high power HVV1011-035 device is a high voltage silicon enhancement mode RF transistor designed for L-Band pulsed avionics applications operating over the frequency range from 1030MHz to 1090MHz.

FEATURES

- · High Power Gain
- Excellent Ruggedness
- 48V Supply Voltage

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	95	V
V_{GS}	Gate-Source Voltage	10	٧
I_{DSX}	Drain Current	2	Α
$P_D^{1,2}$	Power Dissipation	116	W
T _S	Storage Temperature	-65 to	°C
		+200	
T _J	Junction	200	°C
	Temperature		

THERMAL CHARACTERISTICS

Symbol	Parameter	Max	Unit
θ_{1C}^{1}	Thermal Resistance	1.5	°C/W

PACKAGE



The device resides in a Surface Mount Package with a ceramic lid. The SM200 package style is qualified for gross leak test – MIL-STD-883, Method 1014.

RUGGEDNESS

The HVV1011-035 device is capable of withstanding an output load mismatch corresponding to a 20:1 VSWR at all phase angles and rated output power and operating voltage across the frequency band of operation

Symbol	Parameter	Test Condition	Max	Units
LMT^1	Load	F = 1060MHz	20:1	VSWR
	Mismatch			
	Tolerance			

ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	Тур	Units
$V_{BR(DSS)}$	Drain-Source Breakdown	VGS=0V,ID=2mA	102	V
I_{DSS}	Drain Leakage Current	VGS=0V,VDS=48V	<25	μΑ
I_{GSS}	Gate Leakage Current	VGS=5V,VDS=0V	<1	μΑ
G_P^{-1}	Power Gain	P _{OUT} =35W,F=1060MHz	20	dB
IRL^1	Input Return Loss	P _{OUT} =35W,F=1060MHz	8	dB
$\theta_{\rm JC}^{1}$	Drain Efficiency	P _{OUT} =35W,F=1060MHz	52	%
PD^1	Pulse Droop	P _{OUT} =35W,F=1060MHz	<0.2	dB

 1 Under Pulse Conditions: Pulse Width = 50 µsec, Pulse Duty Cycle = 5% at VDD = 48V, IDQ = 15mA 2 Rated at TCASE = 25°C

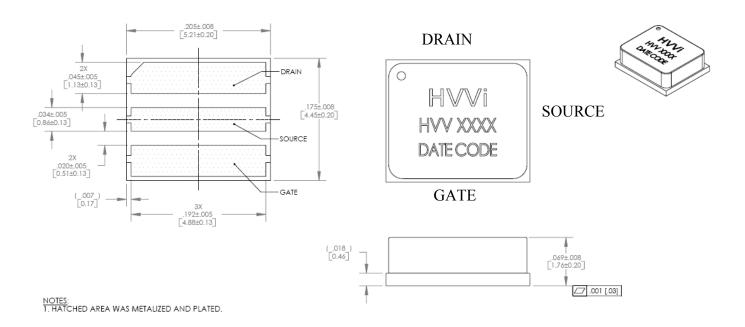


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PACKAGE DIMENSIONS



Note: Drawing is not actual size.

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